

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	((("6063650") or ("6277225"))).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/08 11:28
S2	10567	(257/782,701,702,778,698,678,692,690,778,787,704).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/07 19:05
S4	142	S2 and (bond adj pad electrode metal adj pad) and (die IC integrated adj circuit chip) and substrate and passivat\$3 and (underfill)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 15:41
S5	10567	(257/782,701,702,778,698,678,692,690,778,787,704).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/08 11:41
S6	750	S5 and (bond adj pad electrode metal adj pad) and (die IC integrated adj circuit chip) and substrate and passivat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 10:23
S7	2167	(257/678).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/08 16:32
S8	4821	(257/690,701,723,734).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/08 17:49
S9	1636	S8 and (substrate) and (die chip IC integrated adj circuit) and (bond adj pad metal adj pad electrode) and (passivat\$4 dielectric insulat\$3 oxide nitride)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 17:51
S10	4829	(257/690,701,723,734).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/09 10:15
S11	394	S10 and (bond\$3 adj pad metal adj pad electrode) and (substrate) and (IC integrated adj chip chip die) and (passivat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 10:17

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S12	1765	S10 and (bond\$3 adj pad metal adj pad electrode) and (substrate) and (IC integrated adj chip chip die) and (passivat\$3 dielectric insulat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 13:17
S13	1989	(257/787).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/09 13:18
S16	1	("20030127717").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/09 15:00
S18	1465	(bond\$3 adj pad metal adj pad) and (die IC integrated adj circuit chip) and substrate and passivat\$3 and (underfill encapsula\$4) and (contact adj pad electrode)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 16:14
S20	1	("6040235").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/09 16:23
S21	10583	(257/782,701,702,778,698,678,692,690,778,787,704).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/10 10:26
S25	614	(257/781).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/13 12:47
S27	1	("6734572").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/13 13:02